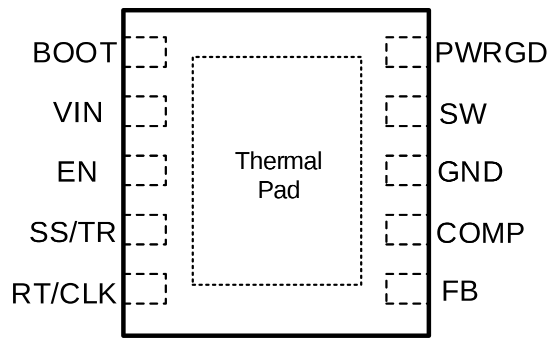
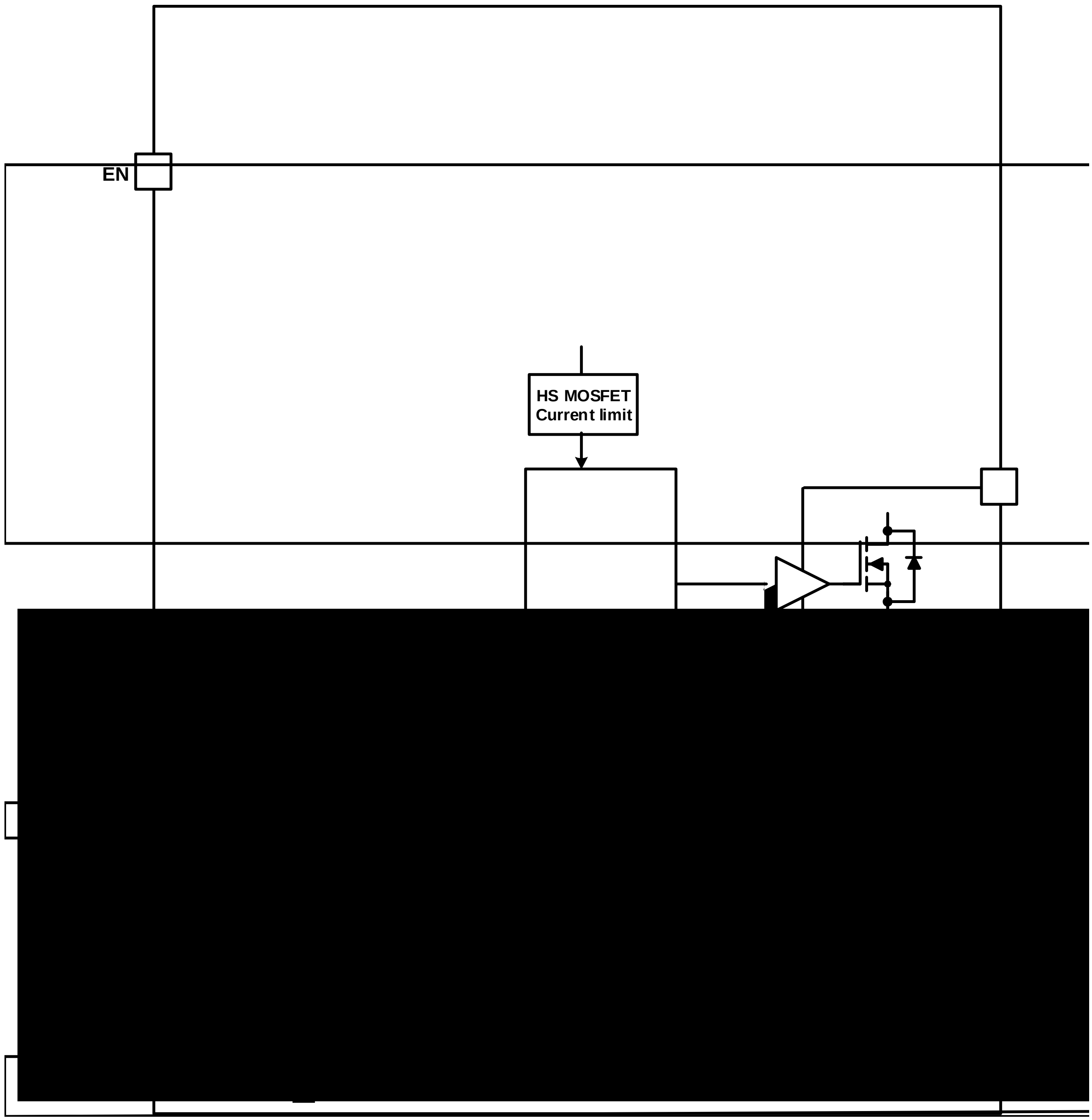
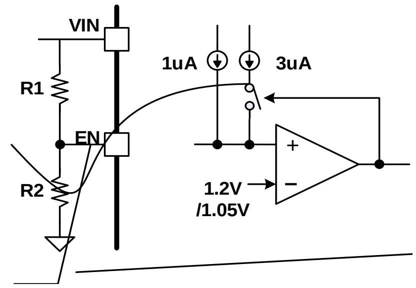
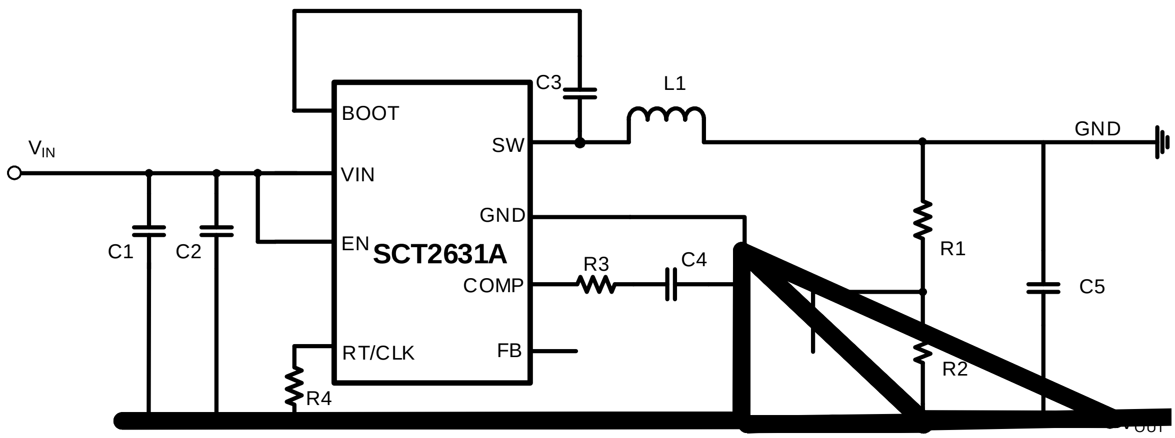
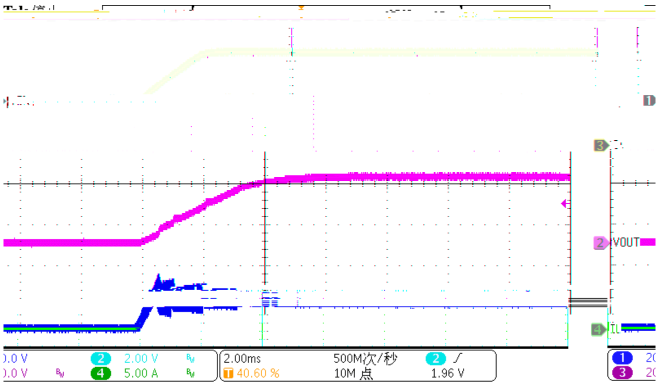
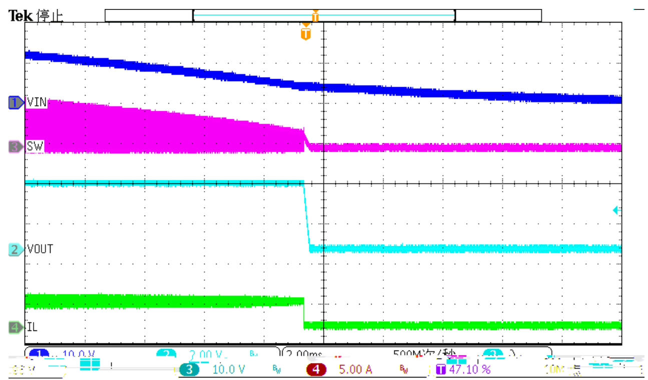

BOOT
VIN
EN
SS/TR
RT/CLK
Thermal
Pad
PWRGD
SW
GND
COMP
FB

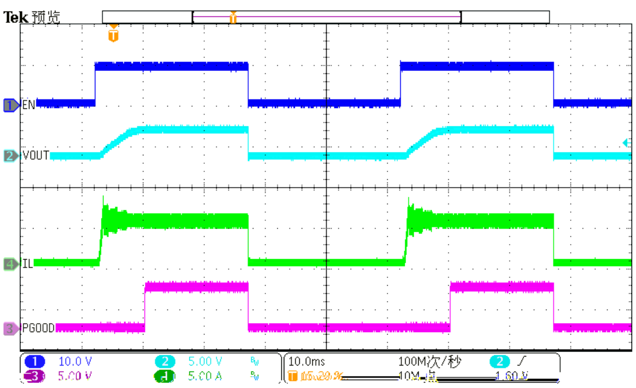

EN
HS MOSFET
Current limit

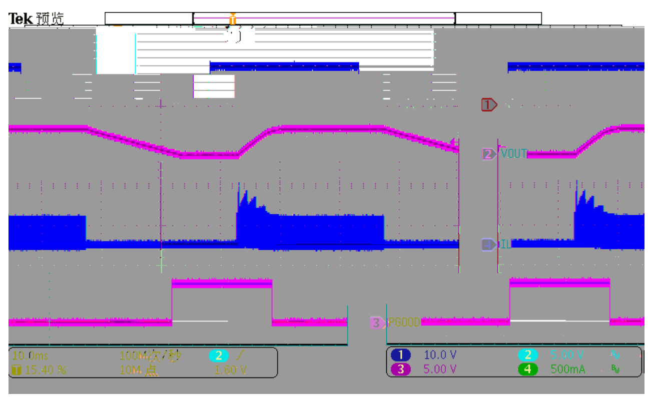

VIN
R1
EN
R2
1uA
3uA
+
−
1.2V
/1.05V

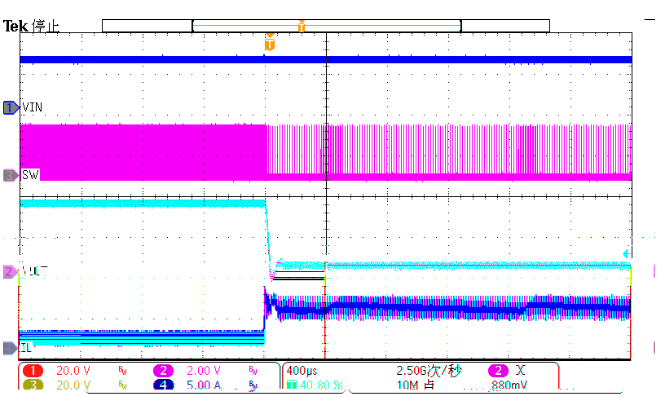

VIN
BOOT
C3
L1
SW
GND
VIN
GND
EN
SCT2631A
COMP
R3
C4
R1
C5
C1
C2
RT/CLK
FB
R2
R4

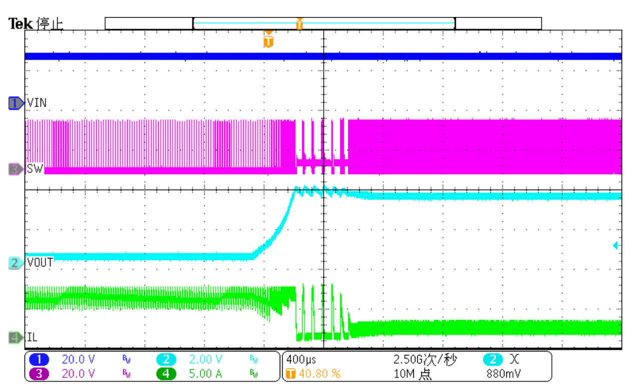

VOUT
IL
2.00ms
500M次/秒
10M 点
1.96 V

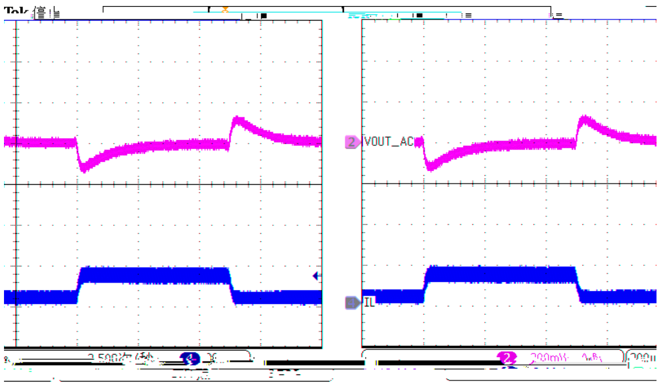

Tek 停止
VIN
SW
VOUT
IL
10.0 V
5.00 A
47.10 %

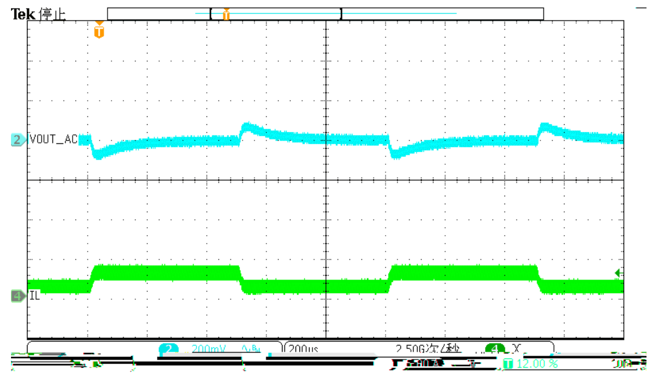

Tek 预览
EN
VOUT
IL
PGOOD
10.0 V
5.00 V
5.00 V
5.00 A
10.0ms
100M次/秒
1.60 V

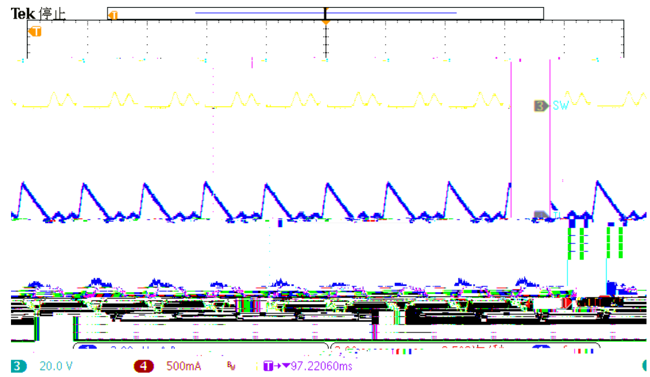

Tek 预览
VOUT
PGOOD
10.0 V
5.00 V
500mA

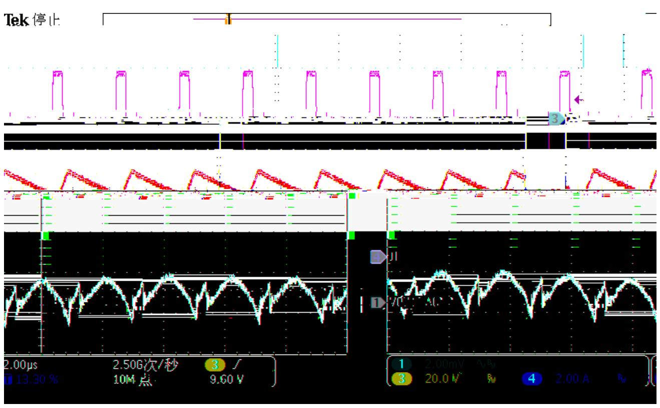

Tek 停止
VIN
SW
IL
20.0 V
2.00 V
20.0 V
5.00 A
400μs
2.50G次/秒
10M 点
880mV


Tek 停止
VIN
SW
VOUT
IL
20.0 V
2.00 V
20.0 V
5.00 A
400μs
40.80 %
2.50G次/秒
10M 点
880mV

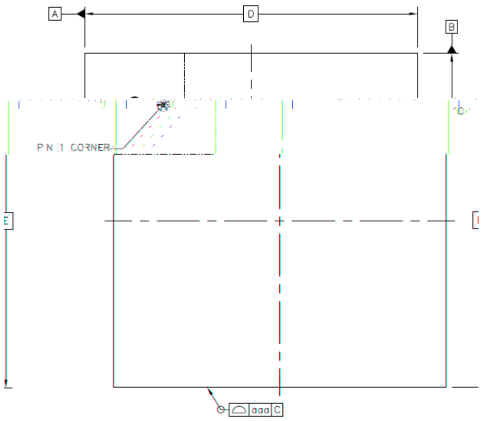

Tek 停止
VOUT_AC
IL

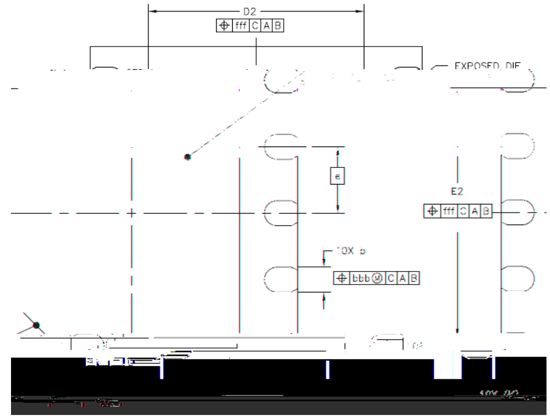

Tek 停止
VOUT_AC
IL
200µs

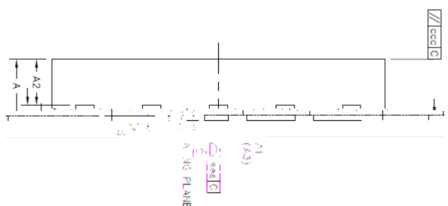

Tek 停止
SW
20.0 V
500mA
97.22060ms


Tek 停止
2.00µs
2.50G次/秒
10M 点
9.60 V
20.0 V

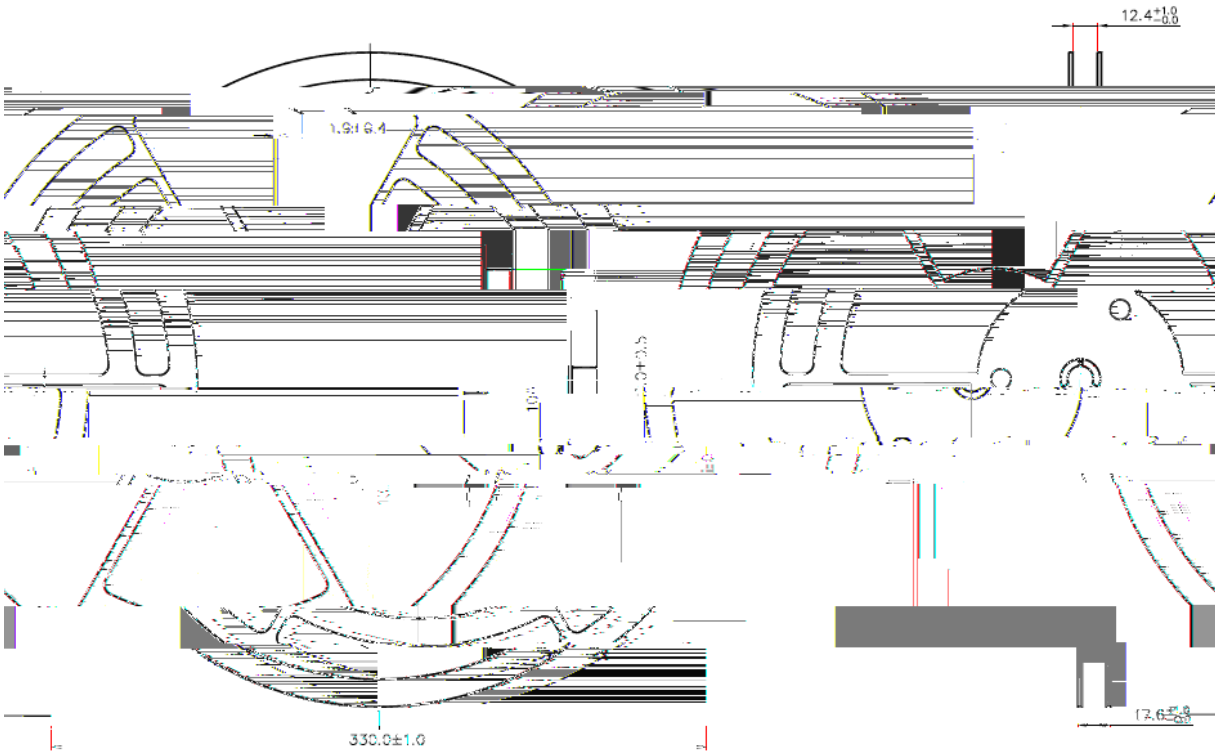

FLUKE
63.6°C
自动 1

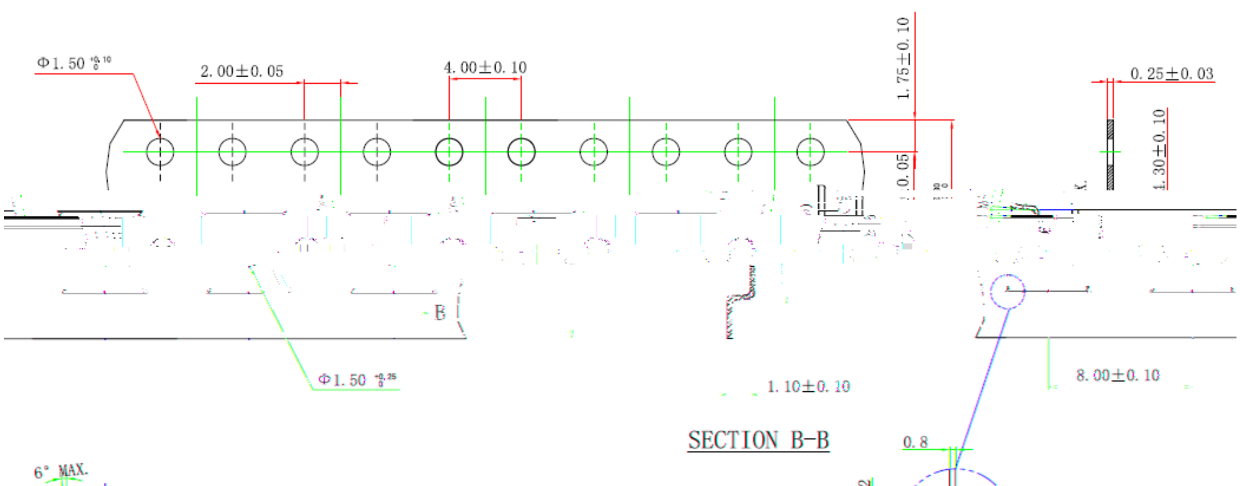






1. Drawing proposed be made a JEDEC package utine MO - 220 variation.
2. Drawing not to scale.
3. All linear dimensions re in millimeters.
4. Thermal pad hall be soldered gn the board.
5. Dimensions f exposed pad gn bottom f package o ot include mold flash.
6. Contact PCB board fabrication for minimum solder mask web Sglerances between the pins.


12.4+1.0 -0.0
1.9±0.4
330.0±1.0
17.6


Φ1. 50 +0.10 0
2. 00±0. 05
4. 00±0. 10
1. 75±0. 10
0. 25±0. 03
1. 30±0. 10
B
Φ1. 50 +0.25 0
1. 10±0. 10
8. 00±0. 10
SECTION B-B
0. 8
6° MAX.